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COPY OF PAPERS
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2814 #10
Attorney Docket SEL 144

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of

Hiroki ADACHI

09/437649
Serial No.: 09/441,026

Filed: November 16, 1999

For: Exposure Device,
Exposure Method And Method)
of Manufacturing
Semiconductor Device

Art Unit: 2814

Examiner: S. Rao

Commissioner for Patents
Washington, D.C. 20231

09/437,649
I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
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the Commissioner for Patents, Washington, D.C. 20231 on
June 26, 2002

Rebecca Hammerquist

Signature Date 6/26/02

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PETITION FOR WITHDRAWAL OF ABANDONMENT

Sir:

~~OK to Enter~~

PETITION

1. Applicant hereby petitions that the abandonment set forth in the notice mailed by the Patent Office on June 18, 2002 be withdrawn.

07/06/2002 00000001 09441026

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SUBMISSION

2. Submitted herewith is:
 - (a) A copy of Election and Amendment mailed on November 1, 2001, which is a complete response to the Restriction Requirement of October 1, 2001, showing a Certificate of Mailing of November 1, 2001.

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- (b) A copy of the post card identifying the above paper filed with the PTO and showing the US PTO receipt stamp dated January 9, 2002.
3. As a complete response to the Office Action was filed with the appropriate extension of time prior to the expiration date, the abandonment of this file was incorrect.
4. Please withdraw the abandonment of this file and proceed with further examination on the basis of the attached copy of the papers as originally filed.

PETITION FEE

5. The petition fee is paid as follows:
- X Enclosed please find a check for \$130.00
6. Please charge our deposit account 50/1039 for any deficiency or credit this account for any overpayment or refund for this petition.

REQUEST FOR REFUND OF PETITION FEE

7. As no defect exists in applicant's previous submission, a refund of the petition fee submitted herewith is respectfully requested.


REQUEST FOR ACKNOWLEDGMENT OF WITHDRAWAL OF ABANDONMENT

8. Acknowledgment of the active status of this application is respectfully requested.

Favorable consideration is earnestly solicited.

Respectfully submitted,

Date: June 26, 2002


Mark J. Murphy
Registration No.: 34,225

COOK, ALEX, McFARRON, MANZO,
CUMMINGS & MEHLER, LTD.
200 West Adams Street
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COPY OF PAPERS
ORIGINALLY FILED

Attorney Docket SEL 144

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of

HIROKI ADACHI

Serial No.: 09/441,022

09/437649

Filed: November 16, 1999

For: Exposure Device,
Exposure Method And
Method of Manufacturing
Semiconductor Device

Art Unit: 2814

Examiner: S. Rao

Commissioner for Patents
Washington D.C. 20231



I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:
the Commissioner for Patents, Washington, D.C. 20231 on
November 1, 2001
MARK J. MURPHY
11-1-01
Signature Date

ELECTION AND AMENDMENT

Sir:

In response to the Restriction Requirement October 1, 2001, Applicant elects to prosecute Group III: Claims 8-33 in the above-identified application. Applicant is making this election without prejudice to later filing a divisional application on the non-elected claims.

Please also amend the above-identified application as follows:

IN THE CLAIMS:

Please add the following new claims:

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34. (New) A method of manufacturing a semiconductor device, comprising steps of:
forming a pattern comprising a light-shielding film over a front side of a
light transmissive substrate;

forming a photosensitive film over said pattern;

preparing a reflecting means located opposite to said photosensitive film;

preparing a light source for emitting a light; and

exposing said photosensitive film by irradiating it from a back side of said
substrate with said light emitted from said light source while using said pattern as a mask
wherein a reflecting means reflects a light passing through said photosensitive film, thereby said
photosensitive film is irradiated from the front side of said substrate with the light and is
exposed.

35. (New) A method of manufacturing a semiconductor device, comprising steps of:
forming a pattern comprising a light-shielding film over a front side of a light transmissive
substrate;

forming a photosensitive film over said pattern;

preparing a reflecting means located opposite to said photosensitive film;

preparing a light source for emitting a light; and

exposing said photosensitive film by irradiating it from a back side of said
substrate with said light emitted from said light source while using said pattern as a mask
wherein a reflecting means reflects a light passing through said photosensitive film, thereby said
photosensitive film is irradiated from the front side of said substrate with the light and is
exposed.


36. (New) A method according to claim 35, wherein a shape of the photosensitive film over said pattern corresponds to a reduced shape of said pattern comprising the light-shielding film.

Please discharge Deposit Account No. 50-1039 for any fee due for this amendment.

Favorable consideration is earnestly solicited.

Respectfully submitted,

Dated: November 1, 2001


Mark J. Murphy
Registration No. 34, 225

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